

APGB0607B7R23C

0.65 x 0.65 x 0.25 mm Bi-Color Surface Mount LED



DESCRIPTIONS

- The Blue source color devices are made with InGaN on Sapphire substrate Light Emitting Diode
- The Hyper-Red source color devices are made with AlGaInP on GaAs substrate Light Emitting Diode
- · Electrostatic discharge and power surge could damage the LEDs
- It is recommended to use a wrist band or anti-electrostatic glove when handling the LEDs
- All devices, equipments and machineries must be electrically grounded

FEATURES

- 0.65 mm x 0.65 mm SMD LED, 0.25 mm thickness
- Low power consumption
- Package: 4000 pcs / reel
- Moisture sensitivity level: 3
- Halogen-free
- RoHS compliant

APPLICATIONS

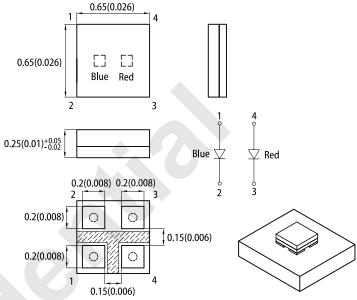
- Backlight
- · Status indicator
- Home and smart appliances
- · Wearable and portable devices
- · Healthcare applications

ATTENTION

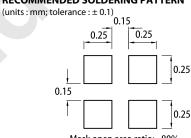
Observe precautions for handling electrostatic discharge sensitive devices



PACKAGE DIMENSIONS



RECOMMENDED SOLDERING PATTERN



Mask open area ratio: 80% Mask thickness: 80~100um

Notes:

- oles. . All dimensions are in millimeters (inches). . Tolerance is ±0.1(0.004") unless otherwise noted
- 3. The specifications, characteristics and technical data described in the datasheet are subject to
- The specifications, crief exercises and reministrate data executions that the specifications change without prior notice.

 The device has a single mounting surface. The device must be mounted according to the specifications.

SELECTION GUIDE

Part Number	Emitting Color (Material)	Lens Type	Iv (mcd) @ 5mA [2]		Viewing Angle [1]	
			Min.	Тур.	201/2	
APGB0607B7R23C	■ Blue (InGaN)	- Water Clear	20	40		
			*20	*40	140°	
	■ Hyper Red (AlGaInP)		30	75		
			*8	*25		

Notes.

1. 61/2 is the angle from optical centerline where the luminous intensity is 1/2 of the optical peak value.

2. Luminous intensity / luminous flux: +/-15%.

* Luminous intensity value is traceable to CIE127-2007 standards.





ELECTRICAL / OPTICAL CHARACTERISTICS at T_A=25°C

Parameter	Symbol	Emitting Color	Value		Unit
raiametei	Symbol	Emitting Color	Тур.	Max.	Uill
Wavelength at Peak Emission I _F = 5mA	λ_{peak}	Blue Hyper Red	463 632	-	nm
Dominant Wavelength I _F = 5mA	λ _{dom} ^[1]	Blue Hyper Red	468 624	-	nm
Spectral Bandwidth at 50% Φ REL MAX I _F = 5mA	Δλ	Blue Hyper Red	25 20	-	nm
Forward Voltage I _F = 5mA	V _F ^[2]	Blue Hyper Red	2.9 1.95	3.2 2.3	V
Reverse Current (V _R = 5V)	I _R	Blue Hyper Red	-	50 10	μА
Temperature Coefficient of λ_{peak} I_F = 5mA, -10°C \leq T \leq 85°C	TC_{\lambdapeak}	Blue Hyper Red	0.04 0.13	-	nm/°C
Temperature Coefficient of λ_{dom} I _F = 5mA, -10°C \leq T \leq 85°C	TC_{\lambdadom}	Blue Hyper Red	0.03 0.06	-	nm/°C
Temperature Coefficient of V_F $I_F = 5mA$, -10°C $\leq T \leq 85$ °C	TC _V	Blue Hyper Red	-3.0 -1.9	-	mV/°C

ABSOLUTE MAXIMUM RATINGS at T_A=25°C

Parameter	Complete	Va	11::4		
Parameter	Symbol	Blue	Hyper Red	Unit	
Power Dissipation	P _D ^[1]	3	mW		
Reverse Voltage	V_R	5 5		V	
Junction Temperature	Tj	115	115	°C	
Operating Temperature	T _{op}	-40 To	°C		
Storage Temperature	T _{stg}	-40 To +100		°C	
DC Forward Current	I _F ^[2]	10 10		mA	
Peak Forward Current	I _{FP} ^[3]	50	40	mA	
Electrostatic Discharge Threshold (HBM)	-	250 3000		V	
Thermal Resistance (Junction / Ambient)	R _{th JA} [4]	720	650	°C/W	
Thermal Resistance (Junction / Solder point)	R _{th JS} [4]	580	480	°C/W	

Notes:

1. Within 35mW when multiple chips are lightened

2. The maximum ratings are valid for the case of lighting a single chip
When two chips are lit at the same time, each chip should be driven at a current lower than 50% of the absolute maximum ratings

3. Duty Cycle ≤ 1 / 20, Pulse Width = 1ms.

4. R<sub>th, JA, R_{th, JS} Results from mounting on PC board FR4 (pad size ≥ 16 mm² per pad).

5. Relative humidity levels maintained between 40% and 60% in production area are recommended to avoid the build-up of static electricity – Ref JEDEC/JESD625-A and JEDEC/J-STD-033.</sub>

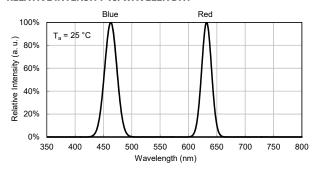


^{1.} The dominant wavelength (λd) above is the setup value of the sorting machine. (Tolerance λd: ±1nm.)
2. Forward voltage: ±0.1V.
3. Wavelength value is traceable to CIE127-2007 standards.
4. Excess driving current and / or operating temperature higher than recommended conditions may result in severe light degradation or premature failure.

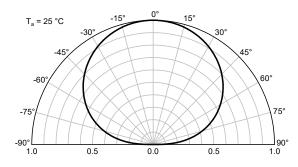


TECHNICAL DATA

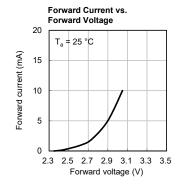
RELATIVE INTENSITY vs. WAVELENGTH

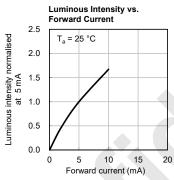


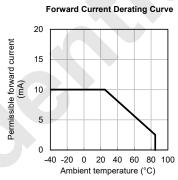
SPATIAL DISTRIBUTION

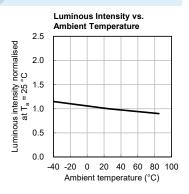


BLUE

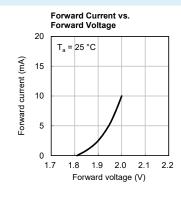


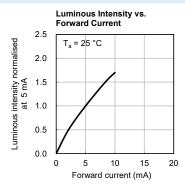


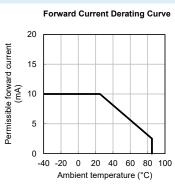


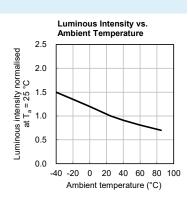


HYPER RED



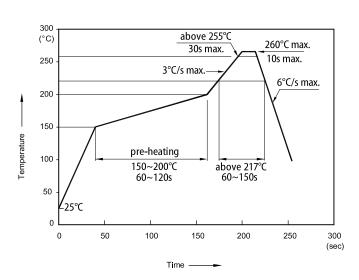






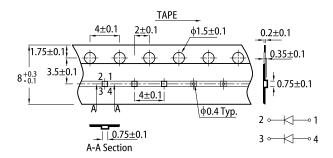


REFLOW SOLDERING PROFILE for LEAD-FREE SMD PROCESS

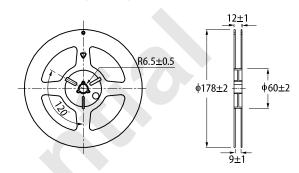


- 1. Don't cause stress to the LEDs while it is exposed to high temperature.
 2. The maximum number of reflow soldering passes is 2 times.
 3. Reflow soldering is recommended. Other soldering methods are not recommended as they might cause damage to the product.

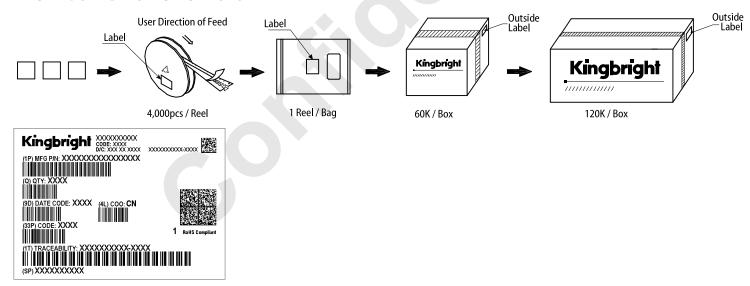
TAPE SPECIFICATIONS (units:mm)



REEL DIMENSION (units: mm)



PACKING & LABEL SPECIFICATIONS



PRECAUTIONARY NOTES

- The information included in this document reflects representative usage scenarios and is intended for technical reference only
- The part number, type, and specifications mentioned in this document are subject to future change and improvement without notice. Before production usage customer should refer to the latest datasheet for the updated specifications.
- When using the products referenced in this document, please make sure the product is being operated within the environmental and electrical limits specified in the datasheet. If
- The information in this document applies to typical usage in consumer electronics applications. If customer's application has special reliability requirements or have life-threatening liabilities, such as automotive or medical usage, please consult with Kingbright representative for further assistance.

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